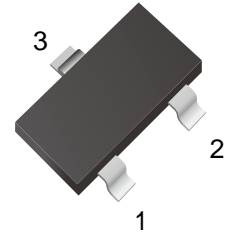


## Zener Diodes

### Features

- Low Zener Impedance
- Power Dissipation of 300mW
- High Stability and High Reliability
- Lead free in comply with EU RoHS 2011/65/EU directives



### Mechanical Data

- Case: SOT-23
- Small Outline Plastic Package
- Package Polarity: Color band denotes cathode end
- Epoxy UL: 94V-0
- Mounting Position: Any
- Approx. Weight: 8.1mg

### Ordering Information

Part Number	Shipping	Reel
LTZ84Cxx-TR3	3000PCS Tape&Reel	7 inches
LTZ84Cxx-TR12	12000PCS Tape&Reel	13 inches

### Maximum Ratings (at 25°C)

Characteristic	Symbol	Value	Unit
Power Dissipation(Note 1)	$P_d$	300	mW
Forward Voltage (Note 2) @ $I_F = 10\text{mA}$	$V_F$	0.9	V
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	417	°C/W
Operation Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	°C

- Notes:
1. Valid provided that device terminals are kept at ambient temperature.
  2. Tested with pulses, period=5ms, pulse width =300 $\mu$ s.
  3. f = 1kHz.

## Electrical characteristics (T<sub>A</sub>=25°C)

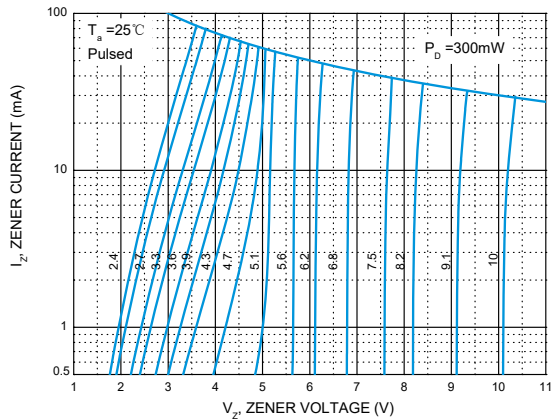
Type Number	Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current		Temperature Coefficient of Zener voltage @ I <sub>ZT</sub> =5mA mV/°C	
		V <sub>Z</sub> @I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	V <sub>R</sub>	Min	Max
		Nom(V)	Min(V)	Max(V)	(mA)	(Ω)		(mA)	(μA)	(V)		
LTZ84C2V4	Z11	2.4	2.20	2.60	5	100	600	1.0	50	1.0	-3.5	0
LTZ84C2V7	Z12	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
LTZ84C3V0	Z13	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
LTZ84C3V3	Z14	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0
LTZ84C3V6	Z15	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0
LTZ84C3V9	Z16	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0
LTZ84C4V3	Z17	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0
LTZ84C4V7	Z1	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2
LTZ84C5V1	Z2	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2
LTZ84C5V6	Z3	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2.0	2.5
LTZ84C6V2	Z4	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7
LTZ84C6V8	Z5	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5
LTZ84C7V5	Z6	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3
LTZ84C8V2	Z7	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2
LTZ84C9V1	Z8	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0
LTZ84C10	Z9	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0
LTZ84C11	Y1	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
LTZ84C12	Y2	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
LTZ84C13	Y3/WK	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
LTZ84C15	Y4	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
LTZ84C16	Y5	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
LTZ84C18	Y6	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
LTZ84C20	Y7	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
LTZ84C22	Y8	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
LTZ84C24	Y9	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
LTZ84C27	Y10	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
LTZ84C30	Y11	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4
LTZ84C33	Y12	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4
LTZ84C36	Y13	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4
LTZ84C39	Y14	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2
LTZ84C43	Y15	43	40.0	46.0	2	100	700	1	0.1	32	10	12

- Notes: 1. Valid provided that device terminals are kept at ambient temperature.  
 2. Tested with pulses, period=5ms,pulse width =300μs.  
 3. f = 1kHz.

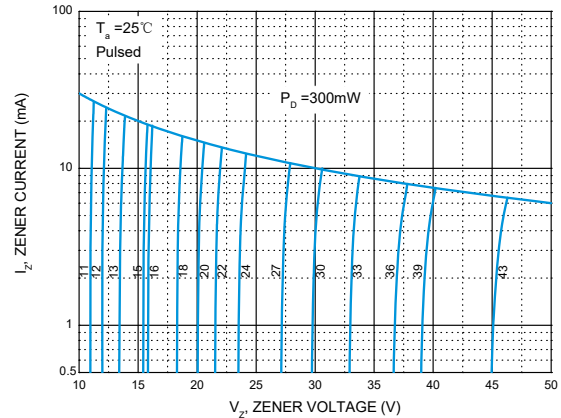


**Characteristics Curves**

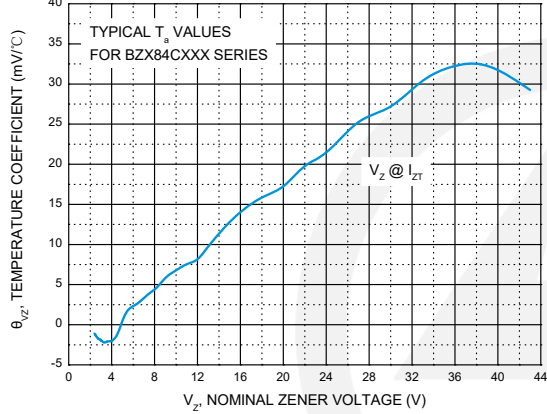
**Zener Characteristics ( $V_z$  Up to 10 V)**



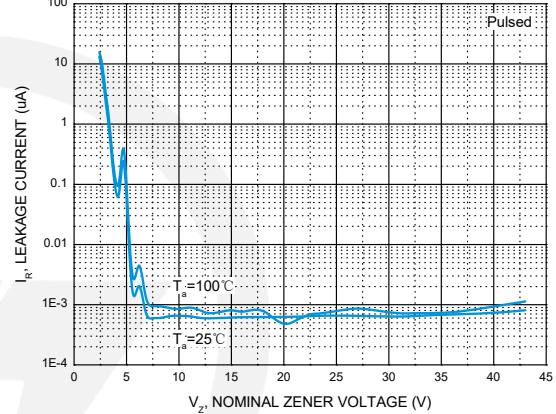
**Zener Characteristics (11 V to 43 V)**



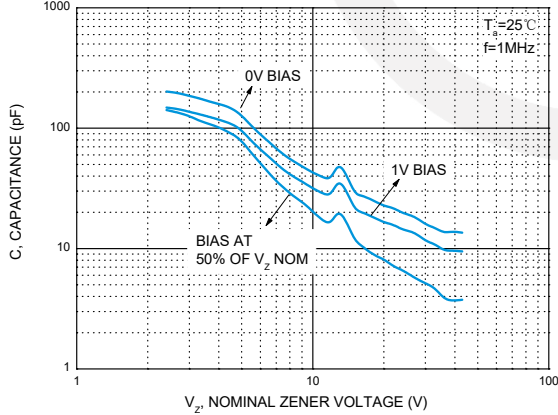
**Temperature Coefficients**



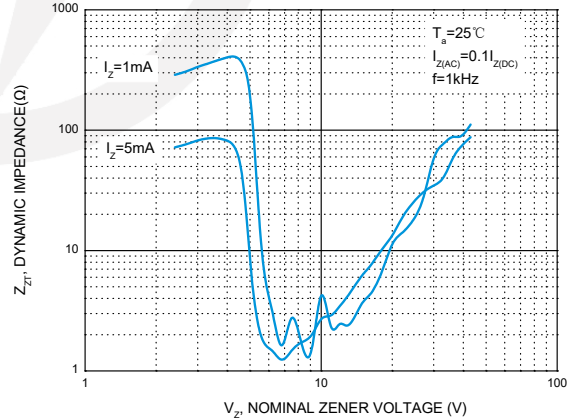
**Typical Leakage Current**



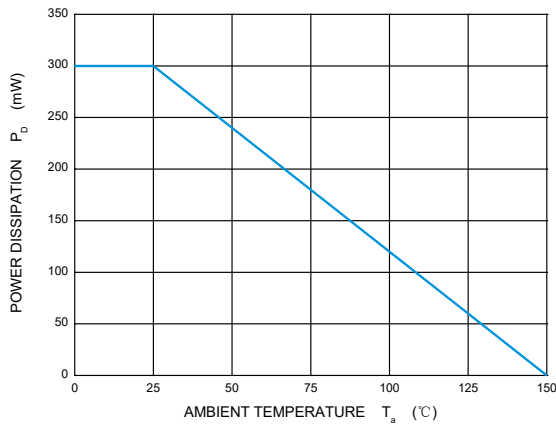
**Typical Capacitance**



**Effect of Zener Voltage on Zener Impedance**

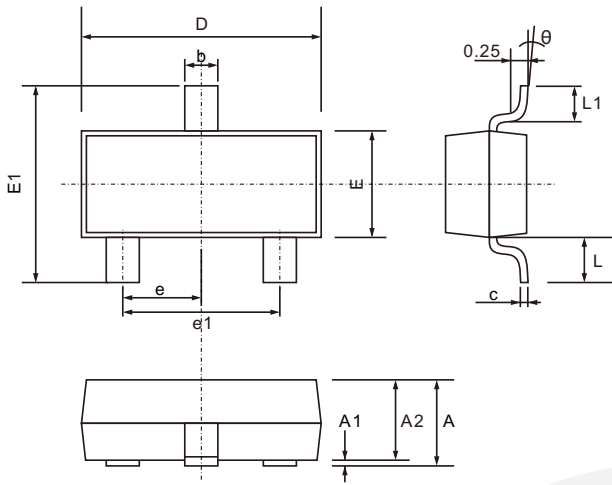


**Power Derating Curve**



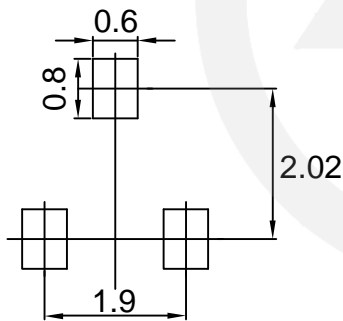
## SOT-23 Package Outline

Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.200
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.200
D	2.700	3.100
E	1.200	1.400
E1	2.200	2.600
e	0.950 TYP.	
e1	1.750	2.050
L	0.550 TYP.	
L1	0.300	0.500
$\theta$	0°	8°

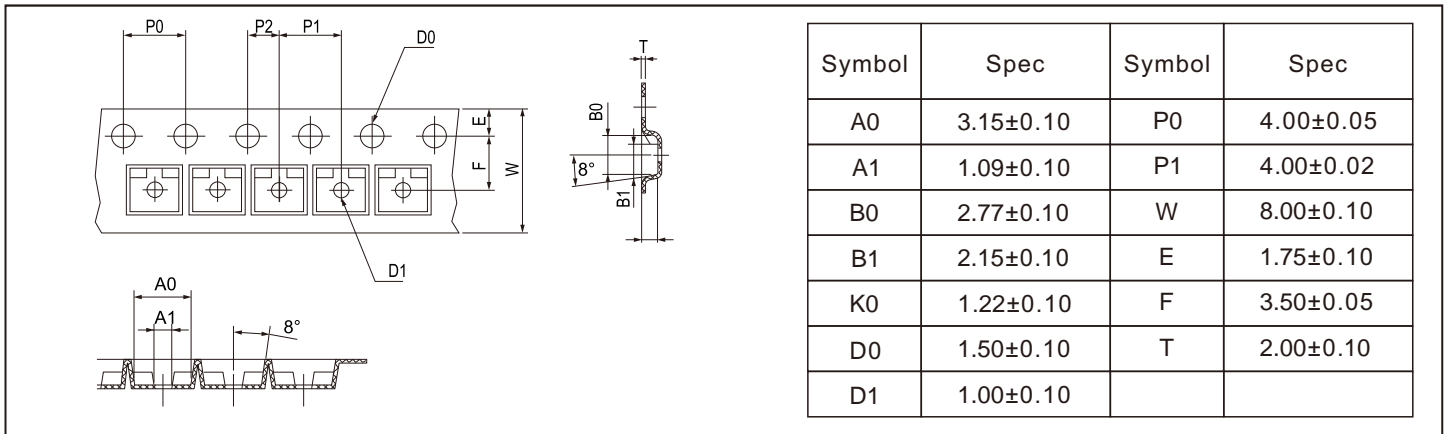
## SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$
  3. The pad layout is for reference purpose only.

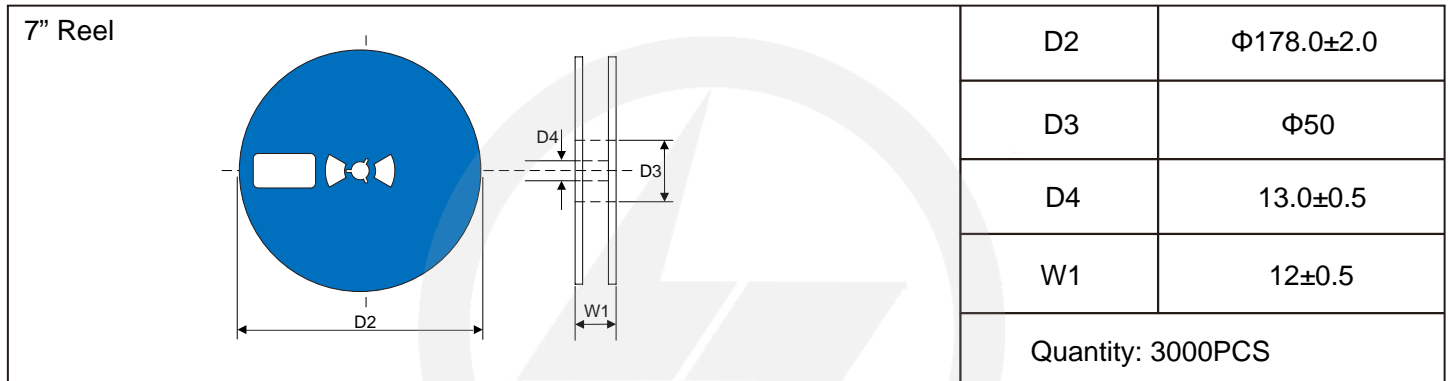
## Carrier Tape Dimensions

Unit : mm



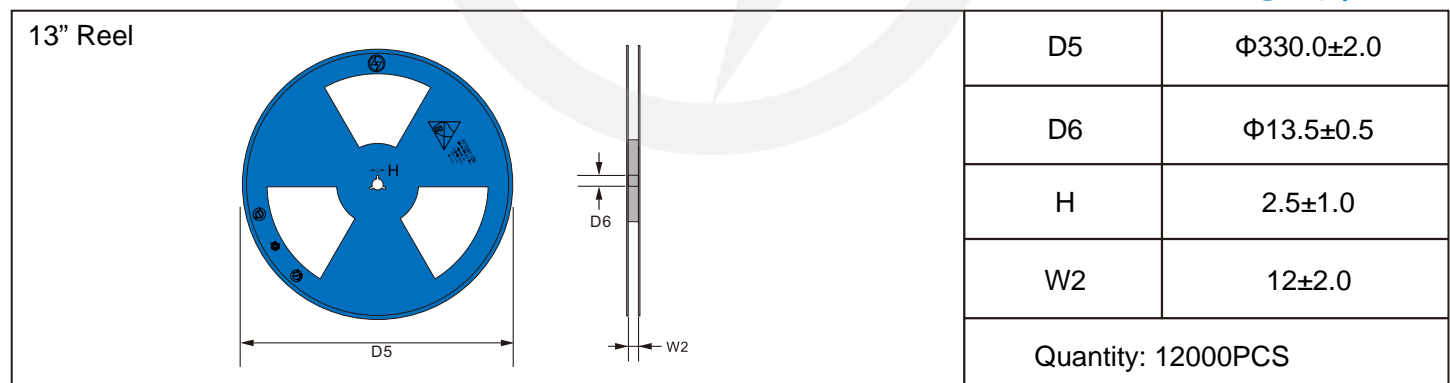
## Reel Dimensions

Unit : mm

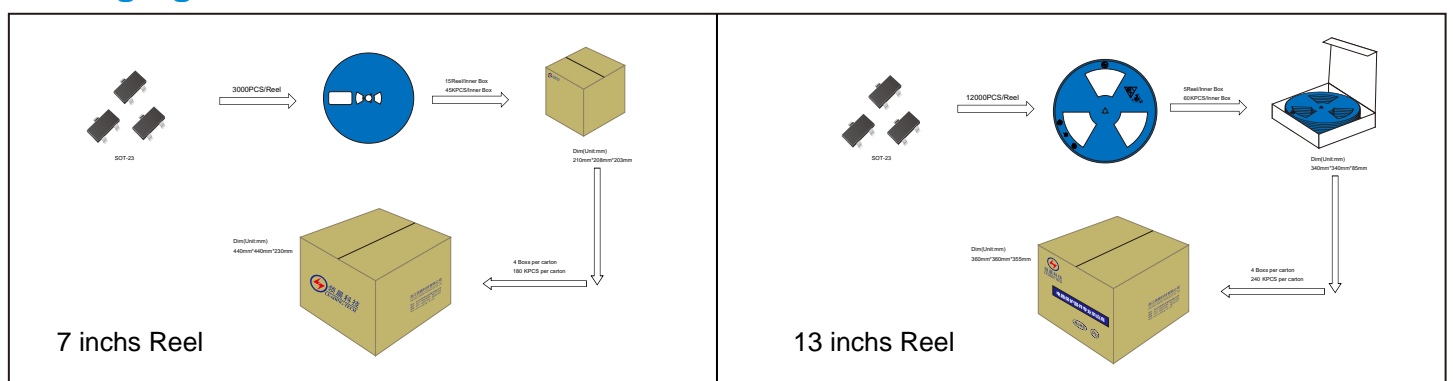


## Reel Dimensions

Unit : mm



## Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second max.
Preheat	
-Temperature Min (T <sub>S min</sub> )	150°C
-Temperature Max (T <sub>S max</sub> )	200°C
-Time (min to max) (t <sub>s</sub> )	60-180 seconds
T <sub>S max</sub> to T <sub>L</sub>	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T <sub>L</sub> )	217°C
-Time (t <sub>L</sub> )	60-150 seconds
Peak Temperature (T <sub>P</sub> )	260°C
Time within 5°C of actual Peak Temperature (t <sub>p</sub> )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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## Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision Content	Revision Reason	Revision Person	Note
01	2024.03.18	2024.03.18	3.0	New file	/	Ding	
02	2025.06.17	2025.06.17	3.1	Update packaging information	/	Ding	
03	2026.03.04	2026.03.04	3.2	Package outline E1(max)=2.6mm	/	Ding	